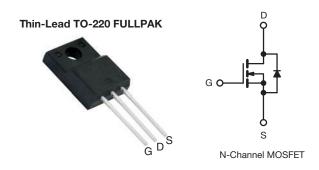


E Series Power MOSFET



PRODUCT SUMMARY		
V _{DS} (V) at T _J max.	70	00
R _{DS(on)} max. (Ω) at 25 °C	$V_{GS} = 10 \text{ V}$	0.6
Q _g max. (nC)	4	8
Q _{gs} (nC)	6	6
Q _{gd} (nC)	1	1
Configuration	Sin	gle

FEATURES

- Low figure-of-merit (FOM) Ron x Qa
- Low input capacitance (Ciss)
- · Reduced switching and conduction losses
- Ultra low gate charge (Q_a)
- Avalanche energy rated (UIS)
- · Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



APPLICATIONS

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Industrial
 - Welding
 - Induction heating
 - Motor drives
 - Battery chargers
 - Renewable energy
 - Solar (PV inverters)

ORDERING INFORMATION	
Package	Thin-Lead TO-220 FULLPAK
Lead (Pb)-free	SiHA6N65E-E3
Lead (Pb)-free and halogen-free	SiHA6N65E-GE3

ABSOLUTE MAXIMUM RATINGS (T _C	= 25 °C, unl	ess otherwis	se noted)		
PARAMETER			SYMBOL	LIMIT	UNIT
Drain-source voltage		V_{DS}	650	V	
Gate-source voltage		V_{GS}	± 30	v	
Continuous drain current (T _{.I} = 150 °C) e	V _{GS} at 10 V	$T_C = 25 ^{\circ}C$ $T_C = 100 ^{\circ}C$		7	
Continuous drain current (1 _J = 150 °C)	V _{GS} at 10 V	T _C = 100 °C	I _D	5	Α
Pulsed drain current ^a			I _{DM}	18	
Linear derating factor			0.63	W/°C	
Single pulse avalanche energy b		E _{AS}	56	mJ	
Maximum power dissipation		P_{D}	31	W	
Operating junction and storage temperature range	T _J , T _{stg}	-55 to +150	°C		
Drain-source voltage slope	T _J = 125 °C		dV/dt 37		V/ns
Reverse diode dV/dt ^d			αν/αι	27	V/11S
foldering recommendations (peak temperature) c For 10 s			300	°C	
Mounting torque	M3 s	screw		0.6	Nm

- a. Repetitive rating; pulse width limited by maximum junction temperature b. $V_{DD}=50$ V, starting $T_J=25$ °C, L=28.2 mH, $R_g=25$ Ω , $I_{AS}=2$ A c. 1.6 mm from case

- $I_{SD} \le I_D$, dl/dt = 100 A/ μ s, starting $I_J = 25$ °C Limited by maximum junction temperature



Vishay Siliconix

THERMAL RESISTANCE RATI	NGS			
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum junction-to-ambient	R _{thJA}	43	65	°C/W
Maximum junction-to-case (drain)	R _{thJC}	3.1	4.0	G/ VV

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static					•		
Drain-source breakdown voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		650	-	-	V
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	Referenc	Reference to 25 °C, I _D = 1 mA		0.73	-	V/°C
Gate-source threshold voltage (N)	V _{GS(th)}	V _{DS} =	· V _{GS} , I _D = 250 μA	2	-	4	V
		V _{GS} = ± 20 V		-	-	± 100	nA
Gate-source leakage	I _{GSS}	,	$V_{GS} = \pm 30 \text{ V}$	-	-	± 1	μΑ
Zava gata valtaga dyain avyyant	1	V _{DS} =	650 V, V _{GS} = 0 V	-	-	1	
Zero gate voltage drain current	I _{DSS}	V _{DS} = 520 V	, V _{GS} = 0 V, T _J = 125 °C	-	-	10	μA
Drain-source on-state resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 3 A	-	0.5	0.6	Ω
Forward transconductance	9 _{fs}	V _{DS}	= 30 V, I _D = 3 A	-	2	-	S
Dynamic		•		•	-	•	
Input capacitance	C _{iss}		$V_{GS} = 0 \text{ V},$ $V_{DS} = 100 \text{ V},$ f = 1 MHz		820	1640	pF
Output capacitance	C _{oss}	Π,			40	80	
Reverse transfer capacitance	C _{rss}	7			4	8	
Effective output capacitance, energy related ^a	C _{o(er)}			-	36	-	
Effective output capacitance, time related ^b	C _{o(tr)}	V _{DS} = 0 V	$V_{DS} = 0 \text{ V to } 520 \text{ V}, V_{GS} = 0 \text{ V}$		117	-	
Total gate charge	Qg			-	24	48	
Gate-source charge	Q _{gs}	V _{GS} = 10 V	$I_D = 3 A, V_{DS} = 520 V$	-	6	-	nC
Gate-drain charge	Q _{gd}	7		-	11	-	
Turn-on delay time	t _{d(on)}	V _{DD} = 520 V, I _D = 3 A,		-	14	28	ns
Rise time	t _r			-	12	24	
Turn-off delay time	t _{d(off)}	V _{GS} =	$V_{GS} = 10 \text{ V}, R_g = 9.1 \Omega$		30	60	
Fall time	t _f	1		-	20	40	
Gate input resistance	R _g	f = 1 MHz, open drain		0.4	1.4	2.7	Ω
Drain-Source Body Diode Characteristic	s						
Continuous source-drain diode current	I _S	MOSFET symbol showing the integral reverse p - n junction diode		=	-	7	
Pulsed diode forward current	I _{SM}			-	-	18	A A
Diode forward voltage	V _{SD}	T _J = 25 °	C, I _S = 3 A, V _{GS} = 0 V	-	0.83	1.3	V
Reverse recovery time	t _{rr}	-		118	237	474	ns
Reverse recovery charge	Q _{rr}	$T_J = 25 ^{\circ}\text{C}, I_F = I_S = 3 \text{A},$ $dI/dt = 100 \text{A/µs}, V_R = 25 \text{V}$		-	2.2	-	μC
Reverse recovery current	I _{RRM}	di/dt =	100 A/hs, . ^B = 52 A	-	16	_	Α

- a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS}



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

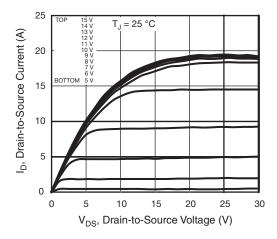


Fig. 1 - Typical Output Characteristics

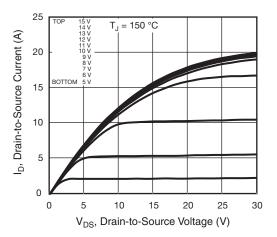


Fig. 2 - Typical Output Characteristics

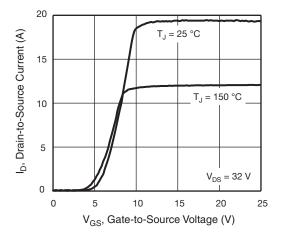


Fig. 3 - Typical Transfer Characteristics

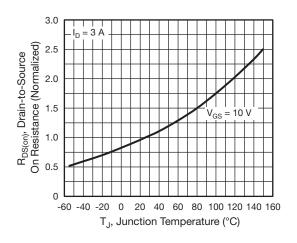


Fig. 4 - Normalized On-Resistance vs. Temperature

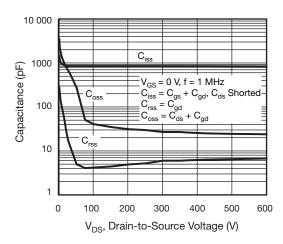


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

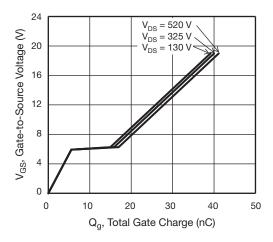


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage



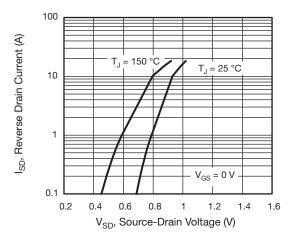


Fig. 7 - Typical Source-Drain Diode Forward Voltage

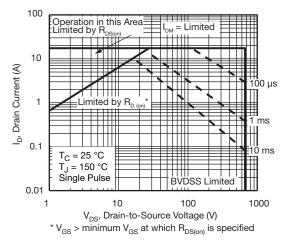


Fig. 8 - Maximum Safe Operating Area

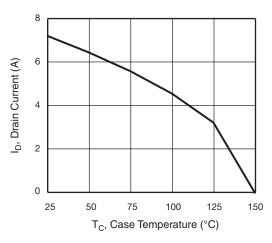


Fig. 9 - Maximum Drain Current vs. Case Temperature

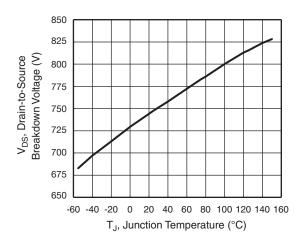


Fig. 10 - Temperature vs. Drain-to-Source Voltage

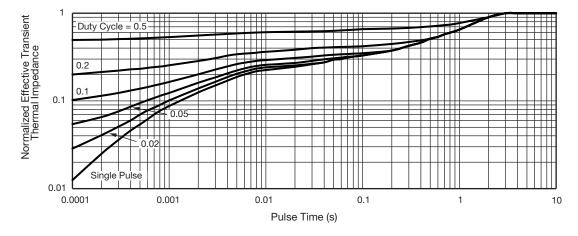


Fig. 11 - Normalized Thermal Transient Impedance, Junction-to-Case



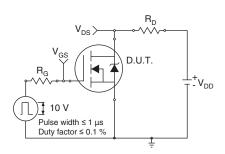


Fig. 12 - Switching Time Test Circuit

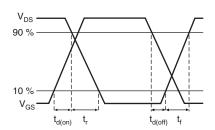


Fig. 13 - Switching Time Waveforms

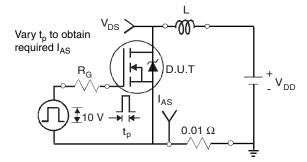


Fig. 14 - Unclamped Inductive Test Circuit

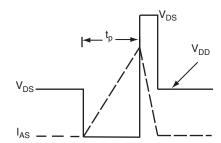


Fig. 15 - Unclamped Inductive Waveforms

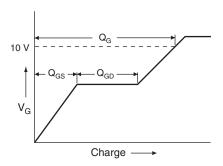


Fig. 16 - Basic Gate Charge Waveform

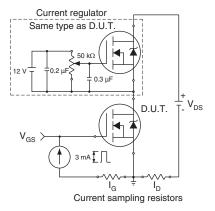
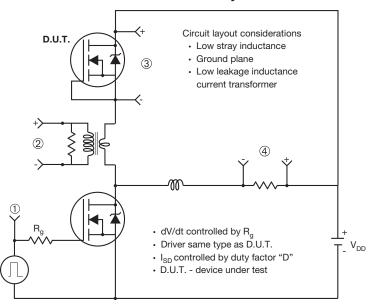


Fig. 17 - Gate Charge Test Circuit



Peak Diode Recovery dV/dt Test Circuit



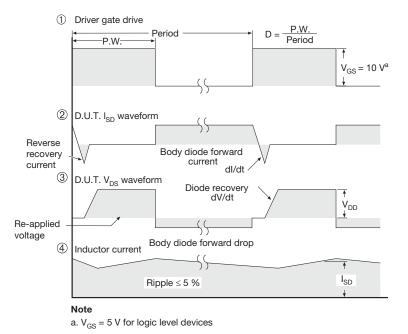


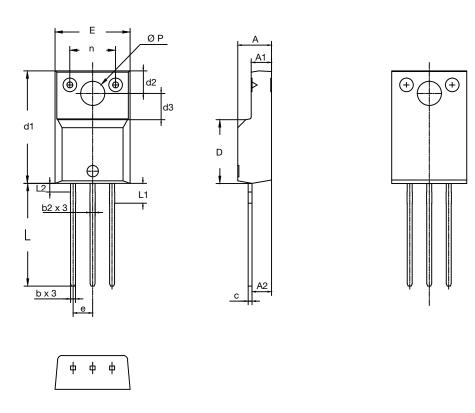
Fig. 18 - For N-Channel

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TO-220 FULLPAK Thin Lead



SYMBOL	MILLIN	METERS	INCHES		
	MIN.	MAX.	MIN.	MAX.	
Α	4.30	4.70	0.169	0.185	
A1	2.50	2.90	0.098	0.114	
A2	2.50	2.70	0.098	0.106	
b	0.60	0.80	0.024	0.031	
b2	0.60	0.90	0.024	0.035	
С	-	0.60	-	0.024	
D	8.30	8.70	0.327	0.342	
d1	14.70	15.30	0.579	0.602	
d2	2.90	3.10	0.114	0.122	
d3	3.40	3.60	0.134	0.142	
Е	9.70	10.30	0.382	0.406	
е	2.50	2.70	0.098	0.106	
L	13.40	13.80	0.528	0.543	
L1	2.50	2.80	0.098	0.110	
L2	-	1.20	-	0.047	
n	6.05	6.15	0.238	0.242	
ØP	3.00	3.40	0.118	0.134	

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